

PCN Number:	20170615006		PCN Date:	June 19 2017												
Title:	Qualification of Additional Assembly site for select Devices															
Customer Contact:	PCN Manager	Dept:	Quality Services													
Proposed 1st Ship Date:	Sept 19 2017	Estimated Sample Availability:	Provided upon Request													
Change Type:																
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials											
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification											
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process											
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process											
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process											
		<input type="checkbox"/>	Part number change													
PCN Details																
Description of Change:																
Texas Instruments is pleased to announce the qualification of PTI as an additional Assembly site for the devices listed below. There are no significant differences in devices built between the two assembly sites.																
Reason for Change:																
Continuity of Supply																
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																
None																
Anticipated impact on Material Declaration																
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .													
Changes to product identification resulting from this PCN:																
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>Assembly Country Code (21L)</th> <th>Assembly City</th> </tr> </thead> <tbody> <tr> <td>JorJin</td> <td>JJN</td> <td>TWN</td> <td>NEW TAIPEI CITY</td> </tr> <tr> <td>PTI</td> <td>PT2</td> <td>TWN</td> <td>HSINCHU CITY</td> </tr> </tbody> </table>					Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City	JorJin	JJN	TWN	NEW TAIPEI CITY	PTI	PT2	TWN	HSINCHU CITY
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City													
JorJin	JJN	TWN	NEW TAIPEI CITY													
PTI	PT2	TWN	HSINCHU CITY													
Sample product shipping label (not actual product label)																



MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM:

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Topside Device marking (if included):

Assembly site code for JJN= T

Assembly site code for PT2 = C

Product Affected

WL1801MODGBMOCR	WL1805MODGBMOCR	WL1831MODGBMOCR	WL1835MODGBMOCR
WL1801MODGBMOCR-WI	WL1805MODGBMOCT	WL1831MODGBMOCT	WL1835MODGBMOCT
WL1801MODGBMOCT			



TI Information
Selective Disclosure

Qualification Report

WL1835 MODULE - 2nd Source Plan - Assy site PTI

This Qualification report qualifies WL1801MOD, WL1805MOD & WL1835MOD for PTI Assembly

Product Attributes

Attributes	Qual Device: WL1835MODGBMOC	QBS Device: WL1837MODGIMOC
Assembly Site	PTI	PTI
Package Family	Module	Module

- QBS: Qual By Similarity
- Qual Device is qualified at MSL LEVEL3-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: WL1835MODGBMOC	QBS Device: WL1837MODGIMOC
PC	Preconditioning Level 3	MSL3, 260C reflow	1/50/0	1/230/0
TC	Temperature Cycle, -40/105	500cy	1/45/0	1/45/0
UHAST	Unbiased Temperature and Humidity, 85C/85%RH	500hr	--	1/45/0
LTSL	Low Temperature Storage Bake -40C	500hr	--	1/45/0
HTSL	High Temperature Bake 105C	500hr	--	1/45/0
VVF	Vibration Variance Frequency	20 - 2000 - 20 Hz Log sweep	--	1/5/0
CDM	ESD CDM	500V	1/3/0	1/3/0
HBM	ESD HBM	1000V	1/3/0	1/3/0

- Preconditioning was performed for Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
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